

Test Report issued under the responsibility of:



## TEST REPORT IEC 60269-4 Low-voltage fuses Part 4: Supplementary requirements for fuse-links for the protection of semiconductor devices

Report Number:	03601-A-23CB0182-S			
Date of issue	2024-04-25			
Total number of pages	29			
Name of Testing Laboratory preparing the Report:				
Applicant's name:	Zhejiang Tengen Electric Co.,Ltd.			
Address:	Sulv Industrial Area, Liushi Town, Yueqing City, Zhejiang Province, P.R.China			
Test specification:				
Standard:	IEC 60269-4:2009, IEC 60269-4:2009/AMD1:2012, IEC 60269-4:2009/AMD2:2016			
	see also IEC 60269-1:2006, IEC 60269-1:2006/AMD1:2009, IEC 60269-1:2006/AMD2:2014			
Test procedure:	CB Scheme			
Non-standard test method:	N/A			
TRF template used	IECEE OD-2020-F1:2022, Ed.1.5			
Test Report Form No	IEC60269_4D			
Test Report Form(s) Originator:	CQC			
Master TRF	Dated 2023-08-17			
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Test item description: Fuse for		or the protection of semiconductor equipment		
Trade Mark TENG		IGEN		
Manufacturer:	Zhejiang Tengen Electric Co.,Ltd.			
	Sulv Industrial Area, Liushi Town, Yueqing City, Zhejiang Province, P.R.China			
Madal/Tena astanana				
Model/Type reference:	TGRS3Z-5EP		1 11 14	
Ratings	See Page 6		1. 7. 4. 1. 6.	
Responsible Testing Laboratory (as applicable), testing procedure and testing location(s):				
		Co., Ltd.(EETI)	us Science Research Institute	
Testing location/ address:		No.7 Yonghe Street, Binhe China	e Road, New District, Suzhou,	
Tested by (name, function, signature) :		Fang Gang (Team leader)	Tok!	
Approved by (name, function, signature) :		Chen Yuan(Supervisor)	As i As	
Testing procedure: CTF Stage 1	:			
Testing location/ address:				
Tested by (name, function, signature) :				
Approved by (name, function, signate	ure):			
Testing procedure: CTF Stage 2:				
Testing location/ address	:			
Tested by (name + signature):				
Witnessed by (name, function, signature). :				
Approved by (name, function, signature) :				
Testing procedure: CTF Stage 3	:			
Testing procedure: CTF Stage 4	:			
Testing location/ address:				
Tested by (name, function, signature) :				
Witnessed by (name, function, signature). :				
Approved by (name, function, signature):				
Supervised by (name, function, signa				

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